

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2442ig#pbf

(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.323799**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004216	1000000	13020.4189453		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.111592	962000	344633.46875		
		Iron (Fe)	7439-89-6	0.000000	0	0		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.003480	30000	10747.4042969		
		Silicon (Si)	7440-21-3	0.000754	1500	537.370239258		
		Magnesium (Mg)	7439-95-4	0.000174	1500	537.370239258		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.116000</b>	<b>1000000</b>	<b>358246.8125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.010584	1000000	32687.2617188		
		<b>External Plating Total:</b>				<b>0.010584</b>	<b>1000000</b>	<b>32687.2617188</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000928	1000000	2865.97460938		
		<b>Internal Plating Total:</b>				<b>0.000928</b>	<b>1000000</b>	<b>2865.97460938</b>
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000137	440000	423.101837158		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000174	560000	537.370239258		
<b>Die Attach Total:</b>				<b>0.000311</b>	<b>1000000</b>	<b>960.472106934</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.025785	135000	79632.703125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.164260	860000	507289.8125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000955	5000	2949.35961914		
		<b>Encapsulation Total:</b>				<b>0.191000</b>	<b>1000000</b>	<b>589871.9375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000760	1000000	2347.13452148		
					<b>TOTAL MASS (g) :</b>	<b>0.323799</b>		